



Product/Process Change Notice - PCN 24_0116 Rev. -

Analog Devices, Inc. One Analog Way, Wilmington, MA 01887, USA

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. An acceptance or concern response should be submitted to ADI promptly. Any requests for samples of changed material or additional information must be made within 30 days of the notification. In accordance with JEDEC Standard 046, customers should acknowledge receipt of the PCN within 30 days of the PCN delivery. ADI contact information is listed below. Note: Revised fields are indicated by a red field name. See Appendix B for revision history.

Lack of acknowledgment of the PCN within 30 days constitutes acceptance of the change. After the acknowledgment, a lack of additional requests within 90 days constitutes acceptance of the change.

PCN Title:	LT8625S - Die Thickness, SMT Paste, and Thermal Parameters Change
Publication Date:	25-Mar-2025
Effectivity Date:	27-Jun-2025 <i>(the earliest date that a customer could expect to receive changed material)</i>
Revision Description:	Initial Release

Description Of Change:

1. Die thickness updated from 450um to 200um and thermal parameters will be changed as shown in attached document.
2. Changed passive component attach material from SnSb5 to SAC305.

Reason For Change:

Die thickness and passive component changes improve manufacturability.

Impact of the change (positive or negative) on fit, form, function & reliability:

The change is transparent in customer applications since there is no change in form, fit, function, quality or reliability of the product.

Product Identification: *(this section will describe how to identify the changed material)*

Production shipment of the product incorporating the new material will begin no sooner than the effective date.

Summary of Supporting Information:

Qualification has been performed per Industry Standard Test Methods. See attached Qualification Results Summary.

Supporting Documents:

Attachment 1: Type: Qualification Results Summary

ADI_PCN_24_0116_Rev_-_RQR11440A.pdf

Attachment 2: Type: Other

ADI_PCN_24_0116_Rev_-_Thermal Analysis Summary - LT8625S.pdf

Note: If applicable, the device material declaration will be updated due to material change.

ADI Contact Information:

For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.

Americas:	Europe:	Japan:	Korea:	Rest of Asia:
PCN_Americas@analog.com	PCN_Europe@analog.com	PCN_Japan@analog.com	PCN_Korea@analog.com	PCN_ROA@analog.com

Appendix A - Affected ADI Models:**Added Parts On This Revision - Product Family / Model Number (2)**

LT8625S / LT8625SIV#TRMPBF

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Appendix B - Revision History:

Rev	Publish Date	Effectivity Date	Rev Description
Rev. -	25-Mar-2025	27-Jun-2025	Initial Release